

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| SCP Global Technologies, Inc. | 10/02/2006 |
| RECEIVING PARTY DATA | |
| Name: | SCP Services, Inc. |
| Street Address: | 6330 Hedgewood Drive, #150 |
| City: | Allentown |
| State/Country: | PENNSYLVANIA |
| Postal Code: | 18106 |
| PROPERTY NUMBERS Total: 3 | |
| Property Type | Number |
| Patent Number: | 6730177 |
| Patent Number: | 6843859 |
| Patent Number: | 6878213 |
| CORRESPONDENCE DATA | |
| Fax Number: | (215)405-3805 |
| <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> | |
| Phone: | 215 977-2205 |
| Email: | kfletcher@wolfblock.com |
| Correspondent Name: | Wolf, Block, Schorr & Solis-Cohen |
| Address Line 1: | 1650 Arch St. - 22nd Floor |
| Address Line 4: | Philadelphia, PENNSYLVANIA 19103 |
| ATTORNEY DOCKET NUMBER: | AKR002-242786 |
| NAME OF SUBMITTER: | Brian L. Belles |
| Total Attachments: 10 | |
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INTELLECTUAL PROPERTY ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, SCP Global Technologies, Inc., a Delaware corporation, and SCP IP, Inc., a Delaware corporation (together, "Assignors"), in connection with that certain Asset Purchase Agreement dated as of September 12, 2006 by and among Assignors, Aktron SCP Acquisition, Inc., a Delaware corporation ("Assignee"), Aktron, Inc., SCP U.S., Inc., SCP Services, Inc., and SCP International Netherlands, B.V., hereby sell, convey, assign, transfer and set over unto Assignee, its successors and assigns, all of its right, title and interest in and to all of the intellectual property held by Assignors, including but not limited to all patents, patent applications listed on Exhibit A and trademarks listed on Exhibit B attached hereto, including all continuations, continuations-in-part, divisionals, foreign counterparts and/or any patents, patent applications or trademarks claiming priority thereto, whether now existing or later filed, together with the goodwill of the business connected therewith, and registrations and applications therefor.

IN WITNESS WHEREOF, this Intellectual Property Assignment has been executed this 2nd day of October, 2006.

SCP GLOBAL TECHNOLOGIES, INC.

By: Keith G. O'Leary
Name: Keith G. O'Leary
Title: Chief Executive Officer

SCP IP, INC.

By: Keith G. O'Leary
Name: Keith G. O'Leary
Title: Executive Vice President

EXHIBIT A

| App # | USPN | Title | Filed |
|-------|-----------|--|------------|
| | 4,860,643 | Ventilated Clean Room Work Station with Aerodynamic Exhaust Baffle | 7/21/1988 |
| | 5,226,242 | Vapor Jet Dryer Apparatus and Method | 2/18/1992 |
| | 5,569,330 | Method and device for chemically treating substrates | 1/13/1995 |
| | 5,744,716 | Fluid Displacement Level, Density and Concentration Measurement System | 6/7/1995 |
| | 5,847,276 | Fluid Displacement Level, Density and Concentration Measurement System | 10/31/1997 |
| | 5,879,484 | Method and device for wet processing substrates in a vessel | 11/12/1997 |
| | 5,882,598 | Wafer Gap Conductivity Cell for Characterizing Process Vessels and Semiconductor Fabrication Processes and Method of Use | 6/7/1996 |
| | 5,902,402 | Device for Chemical Wet Treatment | 7/3/1997 |
| | 5,954,068 | Device and Method for Treating Substrates in a Fluid Container | 5/23/1997 |
| | 5,972,123 | Methods for Treating Semiconductor Wafers | 6/12/1998 |
| | 6,041,938 | Compliant Process Cassette | 8/27/1997 |
| | 6,132,522 | Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing | 7/19/1996 |
| | 6,136,724 | Multiple Stage Wet Processing Chamber | 2/18/1998 |
| | 6,138,694 | Multiple Stage Wet Processing Platform and Method of Use | 3/5/1999 |
| | 6,145,520 | Apparatus for Processing Substrates in a Fluid Tank | 10/23/1998 |
| | 6,153,533 | Method of Using a Compliant Process Cassette | 1/21/1999 |
| | 6,165,912 | Electroless Metal Deposition of Electronic Components in an Enclosable Vessel | 9/14/1999 |
| | 6,170,703 | Chemical Dispensing System and Method | 1/8/1999 |
| | 6,189,552 | Substrate Processing Device | 5/24/1999 |
| | 6,240,938 | Device for Treating Substrates in a Fluid Container | 12/6/1996 |
| | 6,244,282 | Substrate treatment device | 5/1/1999 |
| | 6,245,250 | Process Vessel | 3/5/1999 |
| | 6,264,036 | Process Cassette | 3/5/1999 |
| | 6,257,255 | Substrate treatment device | 4/23/1999 |
| | 6,269,822 | Installation for Wet-Treating Substrates | 3/22/1999 |
| | 6,270,585 | Device and process for treating substrates in a fluid container | 3/19/1999 |
| | 6,286,688 | Compliant Silicon Wafer Handling System | 4/2/1997 |

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| | 6,328,809 | Vapor Drying System and Method | 1/8/1999 |
| | 6,352,064 | Substrate Treatment Device | 4/23/1999 |
| | 6,360,921 | Bellows-Type Dispensing Pump | 6/2/2000 |
| | 6,379,096 | Buffer Storage System | 2/22/2000 |
| | 6,379,470 | Method and Device for Treating Substrates | 8/13/2001 |
| | 6,488,779 | Method and Apparatus for Cleaning Substrates | 12/13/2001 |
| | 6,488,987 | Apparatus and Method for Processing Substrates | 6/22/2001 |
| | 6,491,763 | Processes for Treating Electronic Components | 3/13/2001 |
| | 6,495,099 | Wet Processing Methods for the Manufacture of Electronic Components | 12/10/1998 |
| | 6,523,552 | Facility for Treating Objects in a Process Tank | 10/1/1996 |
| | 6,569,302 | Substrate Carrier | 6/22/2001 |
| | 6,607,604 | Method and Apparatus for Treating Substrates | 6/30/2000 |
| | 6,647,641 | Device and Method for the Treatment of Substrates in a Fluid Container | 12/3/1999 |
| 10/258,559 | 6,706,121 | Device and method for the treatment of semiconductor wafers | 10/23/2002 |
| | 6,730,177 | Method and Apparatus for Washing and/or Drying Using a Revolved Coanda Profile | 7/31/2002 |
| | 6,805,754 | Device and method for treating substrates | 9/28/2001 |
| | 6,378,544 B1 | Pressure Relief Device and Method of Using the Same | 4/19/2000 |
| | 6,246,158 B1 | Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature | 6/2/1999 |
| | 6,378,544 B1 | Pressure Relief Device and Method of Using the Same | 4/19/2000 |
| 09/145,192 US 2001-0047815 | | "Method for treating substrates" (Process sequence for Poseidon Single tank tool) | 9/1/1998 |
| 09/209,101 09/930,009 US 2001-0104552 | 6,495,099 | Wet Processing Methods for the Manufacture of Electronic Components | 12/10/1998 |
| | | System and Methods for Forming Processing Streams | 8/15/2001 |
| 10/031,923 | 6,799,588 | Apparatus for Treating Substrates | 4/17/2002 |
| 10/111,332 | 6,817,369 | Device and method for treating substrates | 4/18/2002 |
| 10/163,441 PrvI was 60/295,919 US 2003-0011774 | | Methods and Systems for Monitoring Process Fluids | 6/4/2002 |
| 10/168,354 US 2002-0189651 | | Apparatus and Method for the Treatment of Substrates | 6/14/2002 |
| 10/169,058 US 2003-0019744 | | Substrate holder | 7/17/2002 |

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| 10/169,060 US 2003-0029480 | | Apparatus for the Treatment of Substrates | 8/22/2002 |
| 10/240,618 US 2003-0108409 | | Method for loading and unloading a processing tank | 11/7/2002 |
| 60/168,487 09/727/661 US 2002-0066717-A1 on 6/6/2002 | | Apparatus for Providing Ozonated Process Fluid and Methods for Using Same | 12/1/2000 |
| 60/270,815 10/074,516 US2002-0119245-A1 | | Method for Etching Electronic Components Containing Tantalum | 2/13/2002 |
| 60/337,208 10/299,308 US 2003-0096457 | | Sonic Transducers Bonded with Polymers and Methods of Making Same for Efficient Sonic Energy Transfer | 11/19/2002 |
| US 2003-0093917 | | Apparatus & Methods for Processing Electronic Component Precursors | 11/21/2002 |

| App # | USPN | Title |
|-------|-----------|--|
| | 4,577,650 | Vessel and system for treating wafers with fluids |
| | 4,633,893 | Apparatus for treating semiconductor wafers |
| | 4,738,272 | Vessel and system for treating wafers with fluids |
| | 4,740,249 | Method of treating wafers with fluid |
| | 4,778,532 | Process and apparatus for treating wafers with process fluids |
| | 4,795,497 | Method and system for fluid treatment of semiconductor wafers |
| | 4,856,544 | Vessel and system for treating wafers with fluids |
| | 4,899,767 | Method and system for fluid treatment of semiconductor wafers |
| | 5,383,484 | Static megasonic cleaning system for cleaning objects |
| | 5,744,716 | Fluid displacement level, density and concentration measurement system |
| | 5,879,464 | Method and device for wet-processing substrates in a vessel |
| | 6,032,662 | Method for sulfuric acid resist stripping |
| | 6,245,158 | Wet processing methods for the manufacture of electronic components using liquids of varying temperature |
| | 6,261,845 | Methods and systems for determining chemical concentrations and controlling the processing of semiconductor substrates |

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| | 6,378,544 | Pressure relief device and method of using the same |
| | 6,517,636 | Method for reducing particle contamination during the wet processing of semiconductor substrates |
| | 6,730,177 | Method and apparatus for washing and/or drying using a revolved coanda profile |
| | 6,843,859 | Dump door |
| | 6,878,213 | Process and system for rinsing of semiconductor substrates |
| | 6,878,213 | Process and system for rinsing of semiconductor substrates |
| 09/905025 | | Vapor drying system and method |
| 10/197384 | | Composition and method for removing photoresist and/or resist residue using supercritical fluids |
| 10/501256 | | Apparatus and method for treating disc-shaped substrate |
| 10/537996 | | Method for drying substrates |
| 10/620895 | | Compositions and method for removing photoresist and/or resist residue at pressures ranging from ambient to supercritical |

| App # | USPN | Title | Filed |
|--------------------------|------|--|------------|
| 09/209,102 | | | 12/1/1998 |
| 09/913,985 | | "Device and method for treating substrates" (Poseidon Double Tank Tool) | 2/1/2000 |
| 09/936,674 | | "Device for treating substrates" (Vertical double process chamber) | Mar 00 |
| 10/110,179 | | "Device and method for treating substrates" (Process rescue function) | 9/1/2000 |
| 10/477,449 | | "Device for wet cleaning of disclike substrates" Single wafer Marangoni | 11/1/2003 |
| 60/135,267 09/574,790 | | Methods for Wet Processing Electronic Components Having Copper Containing Surfaces | 5/19/2000 |
| 60/331,733 10/301,332 | | Apparatus and Methods for Drying Electronic Component Precursors | 11/21/2001 |

EXHIBIT B

| Mark | Juris- diction | Owner Name | Status | Class/s | Appl'n / Regist'n Number | Filing or Reg'n. Date |
|-----------------|-------------------|--|------------|---|--------------------------------|-----------------------------|
| KRONOS | US | Steag Micro Tech GMBH (Assignee in security release: SCP IP, Inc.) | Registered | 7, 11, 37 | 2,558,579 | 4/09/2002 |
| ECO-PLATE | US | Steag Micro Tech GMBH (Assignee in security release: SCP IP, Inc.) | Registered | 7, 37 | 2,630,279 | 10/8/2002 |
| BARRACUDA | US | Steag Micro Tech GMBH (Assignee in security release: SCP IP, Inc.) | Registered | 7, 37 | 2,648,048 | 11/12/2002 |
| ECLIPSE 300 | US | SCP Global Technologies, Inc. | Registered | 7 | 2,627,709 | 10/01/2002 |
| GREENDRY | US | SCP Global Technologies, Inc. | Registered | 7 | 2,741,020 | 07/29/2003 |
| E200 | US | SCP Global Technologies, Inc. | Registered | 7 | 2,537,355 | 02/05/2002 |
| FLUIDCALC | US | SCP Global Technologies, Inc. | Registered | 9 | 2,497,707 | 10/16/2001 |
| ECO-PLATE | S. Korea | SCP Germany GmbH | Registered | 9, 37 | 4500041190000 | 11/07/2001 |
| BARRACUDA | S. Korea | SCP Germany GmbH | Registered | 9, 37, 42 | 4500054830000 | 05/29/2002 |
| DAMAS- CLEAN | S. Korea | SCP Germany GmbH | Registered | 7, 9, 37 | 4500003580000 | 09/02/1999 |
| POSEIDON STT | S. Korea | SCP Germany GmbH | Registered | 35, 36, 37, 39, 40, 41, 42, 43, 44, 45 | 4100543820000 | 04/01/1999 |
| STEAG | S. | Stegeu Hamatek | Registered | 35, 36, 37, | 4100480590000 | 10/12/1998 |

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|--------------------------------|-------------|---|------------|--|---------------|------------|
| HAMATECH & DESIGN | Korea | GmbH SCP Germany GmbH | | 39, 40, 41, 42, 43, 44, 45 | | |
| STEAG HAMATECH & DESIGN | S. Korea | Stegau Hamatek GmbH SCP Germany GmbH | Registered | 7, 8, 9, 10, 11, 17, 21 | 4004258090000 | 10/21/1998 |
| STEAG HAMATECH & DESIGN | S. Korea | Stegau Hamatek GmbH SCP Germany GmbH | Registered | 6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22, 24, 26 | 4004215030000 | 09/16/1998 |
| STEAG & DESIGN | S. Korea | SCP Germany GmbH | Registered | 35, 36, 37, 39, 40, 41, 42, 43, 44, 45 | 4100416890000 | 03/13/1998 |
| STEAG MICROTECH & DESIGN | S. Korea | SCP Germany GmbH | Registered | 6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22, 24, 26 | 4003875250000 | 12/23/1997 |
| STEAG MICROTECH & DESIGN | S. Korea | SCP Germany GmbH | Registered | 7, 8, 9, 10, 11, 17, 21 | 4003790880000 | 10/22/1997 |
| STEAG MICROTECH & DESIGN | S. Korea | SCP Germany GmbH | Registered | 35, 36, 37, 39, 40, 41, 42, 43, 44, 45 | 4100340440000 | 01/08/1997 |
| CAPILLARY COAT | S. Korea | SCP Germany GmbH | Registered | 6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22, 24, 26 | 4003623700000 | 05/19/1997 |
| STEAG MICROTECH | S. Korea | SCP Germany GmbH | Registered | 7, 8, 9, 10, 11, 17, 21 | 4003577270000 | 03/12/1997 |
| STEAG MICROTECH | S. Korea | SCP Germany GmbH | Registered | 6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22, | 4003595750000 | 04/11/1997 |

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*Certificate of Amendment
to the
Certificate of Incorporation
of
AKRION SCP ACQUISITION CORP.*

Pursuant to Section 242 of the General Corporation Law of the State of Delaware

Akrion SCP Acquisition Corp. (the "Corporation"), a corporation organized and existing under the laws of the State of Delaware, hereby certifies as follows:

FIRST: The name of the corporation is Akrion SCP Acquisition Corp. The original Certificate of Incorporation of the Corporation was filed with the Secretary of State of the State of Delaware on November 9, 2005, under the name Akrion SCP Acquisition Corp. (the "Certificate").

SECOND: The Board of Directors of the Corporation adopted a resolution setting forth a proposed amendment to the Certificate, declaring said amendment to be advisable and submitting such resolution to the sole stockholder for approval. The resolution setting forth the proposed amendment is as follows:

RESOLVED, that the Certificate of Incorporation of the Corporation be amended by changing Article FIRST thereof so that, as amended, said Article shall read as follows:

"FIRST: The name of the corporation is SCP Services, Inc."

THIRD: The sole stockholder approved said amendment pursuant to Section 228 of the General Corporation Law of the State of Delaware.

FOURTH: Said amendment was duly adopted in accordance with the provisions of Section 228 and 242 of the General Corporation Law of the State of Delaware.

FIFTH: The capital of the Corporation shall not be reduced under or by reason of said amendment.

IN WITNESS WHEREOF, the Corporation has caused this Certificate of Amendment to the Certificate of Incorporation to be signed by its Chief Financial Officer, this 24 day of October, 2006.

AKRION SCP ACQUISITION CORP.

By: 

W. James Whittle, Chief Financial Officer

Delaware

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The First State

I, HARRIET SMITH WINDSOR, SECRETARY OF STATE OF THE STATE OF DELAWARE, DO HEREBY CERTIFY THE ATTACHED IS A TRUE AND CORRECT COPY OF THE CERTIFICATE OF AMENDMENT OF "AKRION SCP ACQUISITION CORP.", CHANGING ITS NAME FROM "AKRION SCP ACQUISITION CORP." TO "SCP SERVICES, INC.", FILED IN THIS OFFICE ON THE TWENTY-SEVENTH DAY OF OCTOBER, A.D. 2006, AT 1:18 O'CLOCK P.M.

A FILED COPY OF THIS CERTIFICATE HAS BEEN FORWARDED TO THE NEW CASTLE COUNTY RECORDER OF DEEDS.



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Harriet Smith Windsor

Harriet Smith Windsor, Secretary of State

AUTHENTICATION: 5153694

DATE: 10-27-06

PATENT

RECORDED: 04/10/2007

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